

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
KENJI FUKASAWA	05/28/2019
KENJI KATO	05/28/2019
HIROYUKI TAKAHASHI	05/28/2019
YUTAKA HOZUMI	05/30/2019
SUMITAKA ITO	05/30/2019
JUNICHI MIDORIKAWA	06/05/2019
MASAYUKI SASAKI	06/05/2019
RECEIVING PARTY DATA	
Name:	SHOWA CORPORATION
Street Address:	1-14-1, FUJIWARA-CHO
Internal Address:	GYODA-SHI
City:	SAITAMA
State/Country:	JAPAN
Postal Code:	361-8506
Name:	HONDA MOTOR CO., LTD.
Street Address:	1-1, MINAMI-AOYAMA 2-CHOME
Internal Address:	MINATO-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	107-8556
Name:	F-TECH INC.
Street Address:	19, SHOWA-NUMA, SHOBU-CHO
Internal Address:	KUKI-CITY
City:	SAITAMA
State/Country:	JAPAN
Postal Code:	346-0194
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16468248

CORRESPONDENCE DATA**Fax Number:** (202)748-5915

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 202-748-5902**Email:** tsato@kviplaw.com, ip@kviplaw.com**Correspondent Name:** KENEALY VAIDYA LLP**Address Line 1:** 3000 K STREET, N.W.**Address Line 2:** SUITE 200**Address Line 4:** WASHINGTON, D.C. 20007

ATTORNEY DOCKET NUMBER:	5096-0040
NAME OF SUBMITTER:	DAVID J. KENEALY
SIGNATURE:	/david j. kenealy/
DATE SIGNED:	06/19/2019

Total Attachments: 6

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ASSIGNMENT

WHEREAS WE, the below named inventors, [hereinafter referred to as Assignors], have made an invention entitled:

MOTOR DRIVE DEVICE

for which WE filed PCT Application No. PCT/IP2017/047222 on December 28, 2017 and for which WE executed an application for United States Letters Patent concurrently herewith; and

WHEREAS SHOWA CORPORATION, a corporation of Japan, whose post office address is 1-14-1, Fujiwara-cho, Gyodai-shi, Saitama 3618506, JAPAN, HONDA MOTOR CO., LTD., a corporation of Japan, whose post office address is 1-1, Minami-Aoyama 2-chome, Minato-ku, Tokyo 1078556, JAPAN, and E-TECH INC., a corporation of Japan, whose post office address is 19, Showa-numa, Shobu-cho, Kuki-city, Saitama 3460194, JAPAN (hereinafter collectively referred to as Assignee), are desirous of jointly and equally securing and sharing the entire right, title, and interest in and to this invention in all countries throughout the world in equal and joint portion, and in and to the application of United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for and in consideration of the sum of One Dollar (\$1.00) in hand paid and other good and valuable consideration the receipt of which from Assignee is hereby acknowledged, WE, as assignors, have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of such applications, and all applications for Letters Patent which may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent of this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, WE HEREBY covenant that WE have the full right to convey the interest assigned by this Assignment, and WE have not executed and will not execute any agreement in conflict with this Assignment;

AND, WE HEREBY further covenant and agree that WE will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to US respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns;

AND, WE HEREBY authorize and request the attorneys WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. 16/468,248, filed June 10, 2019.) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I have hereunto set my hand.

<u>Full Name of First Assignor</u> Kenji FUKASAWA	<u>Assignor's Signature</u> <i>Kenji Fukasawa</i>	<u>Date</u> <i>28 May 2019</i>
<u>Address:</u> c/o TOCHIGI R&D Center, SHOWA CORPORATION, 112-1, Haga-dai, Haga-machi, Haga-gun, Tochigi 3213325, Japan		<u>Citizenship</u> Japan
Names of additional inventors attached <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No		

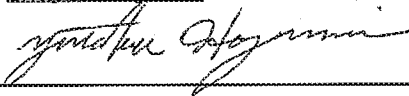
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<u>Full Name of Second Assignor</u> Kenji KATO	<u>Assignor's Signature</u> <i>Kenji Kato</i>	<u>Date</u> <i>28 May 2019</i>
<u>Address:</u> c/o TOCHIGI R&D Center, SHOWA CORPORATION, 112-1, Haga-dai, Haga-machi, Haga-gun, Tochigi 3213325, Japan		<u>Citizenship:</u> Japan
<u>Full Name of Third Assignor</u> Hiroyuki TAKAHASHI	<u>Assignor's Signature</u>	<u>Date</u>
<u>Address:</u> c/o TOCHIGI R&D Center, SHOWA CORPORATION, 112-1, Haga-dai, Haga-machi, Haga-gun, Tochigi 3213325, Japan		<u>Citizenship:</u> Japan
<u>Full Name of Fourth Assignor</u> Yutaka HOZUMI	<u>Assignor's Signature</u>	<u>Date</u>
<u>Address:</u> c/o HONDA R&D CO., LTD., 4-1, Chuo 1-Chome, Wako-shi, Saitama 3510193, Japan		<u>Citizenship:</u> Japan
<u>Full Name of Fifth Assignor</u> Sumitaka ITO	<u>Assignor's Signature</u>	<u>Date</u>
<u>Address:</u> c/o HONDA R&D CO., LTD., 4-1, Chuo 1-Chome, Wako-shi, Saitama 3510193, Japan		<u>Citizenship:</u> Japan
Names of additional inventors attached <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No		

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<u>Full Name of Third Assignor</u> Hiroyuki TAKAHASHI	<u>Assignor's Signature</u> Hiroyuki TAKAHASHI	<u>Date</u> 28-MAY-2019
<u>Address:</u> c/o TOCHIGI R&D Center, SHOWA CORPORATION, 112-1, Haga-dai, Haga-machi, Haga-gun, Tochigi 3213325, Japan		<u>Citizenship:</u> Japan
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Names of additional inventors attached <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No		

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<u>Address:</u> c/o TOCHIGI R&D Center, SHOWA CORPORATION, 112-1, Haga-dai, Haga-machi, Haga-gun, Tochigi 3213325, Japan		<u>Citizenship:</u> Japan
<u>Full Name of Fourth Assignor</u> Yutaka HOZUMI	<u>Assignor's Signature</u> 	<u>Date</u> May 30, 2019
<u>Address:</u> c/o HONDA R&D CO., LTD., 4-1, Chuo 1-Chome, Wako-shi, Saitama 3510193, Japan		<u>Citizenship:</u> Japan
<u>Full Name of Fifth Assignor</u> Sumitaka ITO	<u>Assignor's Signature</u>	<u>Date</u>
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Names of additional inventors attached <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No		

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<u>Address:</u> c/o TOCHIGI R&D Center, SHOWA CORPORATION, 112-1, Haga-dai, Haga-machi, Haga-gun, Tochigi 3213325, Japan		<u>Citizenship:</u> Japan
<u>Full Name of Third Assignor</u> Hiroyuki TAKAHASHI	<u>Assignor's Signature</u>	<u>Date</u>
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<u>Full Name of Fifth Assignor</u> Sumitaka ITO	<u>Assignor's Signature</u> <i>Sumitaka Ito</i>	<u>Date</u> <i>May 30, 2019</i>
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Names of additional inventors attached <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No		

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<u>Full Name of Sixth Assignor</u> Junichi MIDORIKAWA	<u>Assignor's Signature</u> <i>Junichi Midorikawa</i>	<u>Date</u> <i>5, Jun. 2019</i>
<u>Address:</u> c/o Technical Center, F-TECH INC., 196-2, Haga-dai, Haga-machi, Haga-gun, Tochigi 3213325, Japan		<u>Citizenship:</u> Japan
<u>Full Name of Seventh Assignor</u> Masayuki SASAKI	<u>Assignor's Signature</u> <i>Masayuki Sasaki</i>	<u>Date</u> <i>5, Jun. 2019</i>
<u>Address:</u> c/o Technical Center, F-TECH INC., 196-2, Haga-dai, Haga-machi, Haga-gun, Tochigi 3213325, Japan		<u>Citizenship:</u> Japan
<p style="text-align: center;">Names of additional inventors attached <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>		

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